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(71)Applicant : KYOCERA CORP

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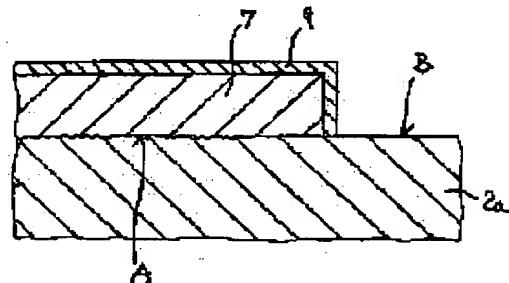
(72)Inventor : YONEDA CHIKAFUMI

(54) MULTILAYER INTERCONNECTION BOARD

(57)Abstract:

PROBLEM TO BE SOLVED: To make bonding pads bond firmly to an uppermost organic resin insulating layer and to make sure an electrical insulation between the bonding pads by a method wherein the surface roughness of the regions, whereon the bonding pads are formed, by uppermost organic resin insulating layer is specified.

SOLUTION: The roughness of the regions A, on where bonding pads 7 are formed, of the upper surface of an uppermost organic resin insulating layer 2a is formed into a roughness of $0.05 \mu m$ Ra $5 \mu m$ in the mean roughness of the roughness in and on the center line of the upper surface and the roughness of the other regions B of the upper surface of the layer 2a is formed into a roughness of Ra $< 5 \mu m$. Owing to this, the bonding area of the layer 2a to the pads 7 is increased, the bonding strength of the pads 7 to the layer 2a becomes a strong one, electrodes on a semiconductor element and the like are made to bond to the pads 7 reliably and firmly and it becomes possible to connect an electronic component, such as the semiconductor element, to thin film wiring conductors reliably and electrically.



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